

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1565	(257/713).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/18 10:39
L2	2490	(438/121,107).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/18 10:39
L3	1951	(438/118).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/18 10:39
L4	157	(257/e51.04).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/18 10:51
L5	2739	(257/e21.505).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/18 10:51
L6	5931	((heat spread\$4 heatspread\$4 thermal \$5) with (semiconductor die chip ic integrated wafer)) and nano\$10 and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 10:53
L7	209	((heat spread\$4 heatspread\$4 thermal \$5) with (semiconductor die chip ic integrated wafer)) and (nano\$10 with acid) and "438"/\$. ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 10:54

L8	22	((heat spread\$4 heatspread\$4 thermal \$5) with (semiconductor die chip ic integrated wafer)) and (nano\$10 with sulfuric) and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 10:55
L9	21	((heat spread\$4 heatspread\$4 thermal \$5) with (semiconductor die chip ic integrated wafer)) and (nano\$10 with nitric) and "438"/\$. ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 10:56
L10	13	((heat spread\$4 heatspread\$4 thermal \$5) with (semiconductor die chip ic integrated wafer)) and (nano\$10 with sulfuric) and "977"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 10:56
L11	23	((heat spread\$4 heatspread\$4 thermal \$5) with (semiconductor die chip ic integrated wafer)) and (nano\$10 with nitric) and "977"/\$. ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 10:57
L12	100	((heat spread\$4 heatspread\$4 thermal \$5) with (semiconductor die chip ic integrated wafer)) and (nano\$10 with acid) and "977"/\$. ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 10:57
L13	324	((heat spread\$4 heatspread\$4 thermal \$5) with (semiconductor die chip ic integrated wafer)) and (nano\$10 with acid) and "257"/\$. ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 10:58

L14	18	((heat spread\$4 heatspread\$4 thermal \$5) with (semiconductor die chip ic integrated wafer)) and (nano\$10 with sulfuric) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 10:58
L15	32	((heat spread\$4 heatspread\$4 thermal \$5) with (semiconductor die chip ic integrated wafer)) and (nano\$10 with nitric) and "257"/\$. ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 10:59
L16	22	((heat spread\$4 heatspread\$4 thermal \$5) with (semiconductor die chip ic integrated wafer)) and (nano\$10 with organic\$4 near3 moiety)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 11:00
L17	67	(carbon and nanotube and sulfuric and nitric). clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 11:31
L18	9	( nanotube with (sulfuric and nitric)). clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 11:32
L19	0	18 and (semiconductor chip die ic integrated). clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 11:32
S1	3951	(257/712,717).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/17 14:35
S2	1886	(257/706).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/17 14:36

S3	934	(257/720).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/18 09:18
S4	1085	(438/122).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/18 09:19
S5	1207	(438/99).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/18 09:21
S6	2	("6989325").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/18 09:22
S7	15	("20010031900"   "20040075464"   "6515339"   "6517995" "6737939"   "6741019").PN. OR ("6989325").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/07/18 09:22
S8	15	("20040152240"   "5457343"   "5805424" "5805426"   "5818700"   "6020747" "6052286"   "6183714"   "6297063" "6322713"   "6340822"   "6429029" "6796897"   "6882051"   "6989325").PN. OR ("7301779").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/07/18 09:23
S9	43	("5346683").PN. OR ("5457343").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/07/18 09:27
S10	262	(257/746).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/18 09:29

S11	132462	nano\$10 and carbon	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 09:45
S12	3576	S11 and "977"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 09:45
S13	6264	nano\$10 and "977"/\$. ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 09:46
S14	3974	S13 and (semiconductor chip die wafer ic integrated)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 09:46
S15	2478	S14 and (sink spread\$4 heatspread\$4 thermal \$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 09:47
S16	134	S14 and ((sink spread \$4 heatspread\$4 thermal\$4) with (gold au))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 09:48
S17	2883	S14 and (sink spread\$4 heatspread\$4 heat thermal\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 09:49
S18	155	S17 and ((sink spread \$4 heatspread\$4 heat thermal\$4) with (gold au))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 09:49
S19	5380	nano\$10 and acid and organic near2 moiety	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 09:54

S20	4281	S19 and (semiconductor chip die wafer ic integrated)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 09:54
S21	4046	S20 and (sink spread\$4 heatspread\$4 heat thermal\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 09:54

7/ 18/ 08 11:35:42 AM

C:\Documents and Settings\Jl m1\My Documents\EAST\Workspaces\10748565.wsp